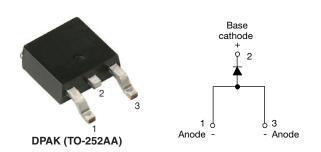
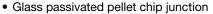


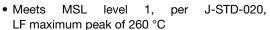
Surface Mount Fast Soft Recovery Rectifier Diode, 8 A



PRIMARY CHARACTERISTICS					
I _{F(AV)}	8 A				
V _R	1200 V				
V _F at I _F	1.3 V				
I _{FSM}	150 A				
t _{rr}	80 ns				
T _J max.	150 °C				
Package	DPAK (TO-252AA)				
Circuit configuration	Single				
Snap factor	0.6				

FEATURES







AEC-Q101 qualified

- Meets JESD 201 class 2 whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V_F rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- On-board and off-board EV / HEV battery chargers
- Renewable energy inverters

DESCRIPTION

The VS-8EWF12SLHM3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

MAJOR RATINGS AND CHARACTERISTICS							
SYMBOL	CHARACTERISTICS	VALUES	UNITS				
I _{F(AV)}	Sinusoidal waveform	8	A				
V _{RRM}		1200	V				
I _{FSM}		150	A				
V _F	8 A, T _J = 25 °C	1.3	V				
t _{rr}	1 A, 100 A/µs	80	ns				
TJ	Range	-40 to +150	°C				

VOLTAGE RATINGS								
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I _{RRM} AT 150 °C mA					
VS-8EWF12SLHM3	1200	1300	4					

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum average forward current	I _{F(AV)}	T _C = 96 °C, 180° conduction half sine wave	8			
Maximum peak one cycle	I _{FSM}	10 ms sine pulse, rated V _{RRM} applied 125		Α		
non-repetitive surge current		10 ms sine pulse, no voltage reapplied	150			
Maximum I ² t for fusing	I ² t	10 ms sine pulse, rated V _{RRM} applied	78	A ² s		
Maximum i-t for fusing	ı-ı	10 ms sine pulse, no voltage reapplied 110		A-5		
Maximum I²√t for fusing	I²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s		



ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST COI	NDITIONS	VALUES	UNITS		
Maximum forward voltage drop	V_{FM}	8 A, T _J = 25 °C		1.3	V		
Forward slope resistance	r _t	T _{.1} = 150 °C		25.6	mΩ		
Threshold voltage	V _{F(TO)}	1J = 150 C		0.93	V		
Maximum reverse leakage current		T _J = 25 °C	V - Poted V	0.1	mA		
iviaximum reverse leakage current	IRM	T _J = 150 °C	V_R = Rated V_{RRM}	4	IIIA		

RECOVERY CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	· •	
Reverse recovery time	t _{rr}	l∈ at 8 A	270	ns	I _{FM}	
Reverse recovery current	I _{rr}	- I _F at 8 A _{pk} 25 Α/μs	4.2	А	$t_a \mid t_b$	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	1	μC	di di Q _{rr}	
Snap factor	S		0.6		l VI,	

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-40 to +150	°C	
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	2.5	°C // //	
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA} (1)		50	°C/W	
Approximate weight			1	g	
Approximate weight			0.03	OZ.	
Marking device		Case style DPAK (TO-252AA)	8EWF12SH		

Note

 $^{^{(1)}}$ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μ m) copper 40 °C/W

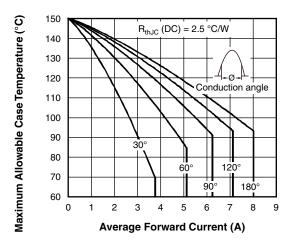


Fig. 1 - Current Rating Characteristics

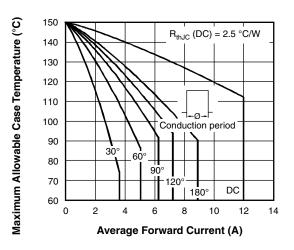


Fig. 2 - Current Rating Characteristics

Maximum Average Forward Power Loss (W)

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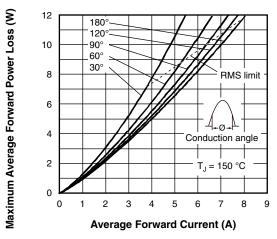


Fig. 3 - Forward Power Loss Characteristics

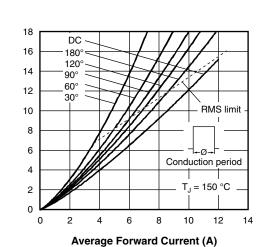


Fig. 4 - Forward Power Loss Characteristics

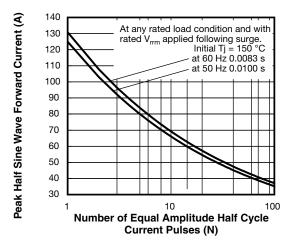


Fig. 5 - Maximum Non-Repetitive Surge Current

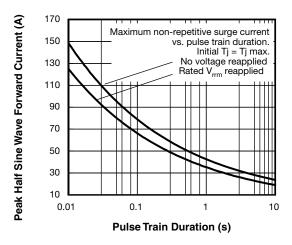


Fig. 6 - Maximum Non-Repetitive Surge Current

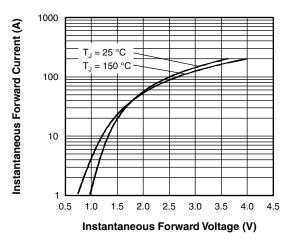


Fig. 7 - Forward Voltage Drop Characteristics

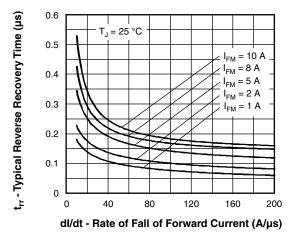


Fig. 8 - Recovery Time Characteristics, T_J = 25 °C

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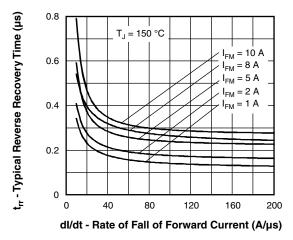


Fig. 9 - Recovery Time Characteristics, T_J = 150 °C

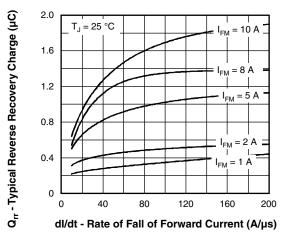


Fig. 10 - Recovery Charge Characteristics, T_J = 25 $^{\circ}$ C

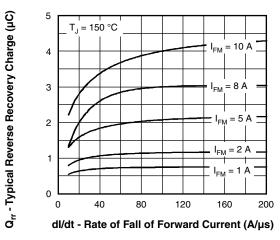


Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

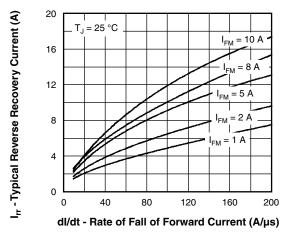


Fig. 12 - Recovery Current Characteristics, $T_J = 25$ °C

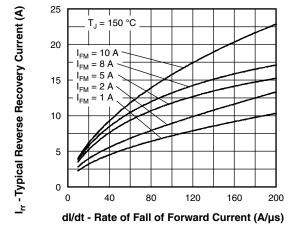


Fig. 13 - Recovery Current Characteristics, $T_J = 150~^{\circ}\text{C}$

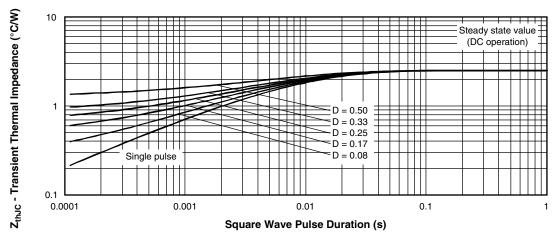
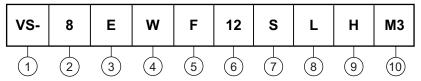


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

3 - Circuit configuration:

E = single

4 - Package:

W = DPAK (TO-252AA)

5 - Type of silicon:

F = fast soft recovery rectifier

6 - Voltage code x 100 = V_{RRM} - 12 = 1200 V

7 - S = surface mountable

8 - L = tape and reel (left oriented), for different orientation contact factory

9 - H = AEC-Q101 qualified

10 - Environmental digit:

M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-8EWF12SLHM3	3000	3000	13" diameter reel			

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95519</u>					
Part marking information	www.vishay.com/doc?95518				
Packaging information	www.vishay.com/doc?96495				
SPICE model	www.vishay.com/doc?97057				



DPAK (TO-252AA)



SYMBOL	MILLIN	METERS INC		MILLIMETERS INCHES		HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	2.18	2.39	0.086	0.094			
A1	1	0.13	-	0.005			
b	0.64	0.89	0.025	0.035			
b2	0.76	1.14	0.030	0.045			
b3	4.95	5.46	0.195	0.215	3		
С	0.46	0.61	0.018	0.024			
c2	0.46	0.89	0.018	0.035			
D	5.97	6.22	0.235	0.245	5		
D1	4.93	-	0.194	-	3		
Е	6.35	6.73	0.250	0.265	5		
E1	4.32	-	0.170	-	3		

SYMBOL	MILLIMETERS		INC	NOTES	
STWIDGE	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108	REF.	
L2	0.51 BSC		0.020	BSC	
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
	•	•		•	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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Vishay

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